

**Normally-On Trench Silicon Carbide Power JFET**

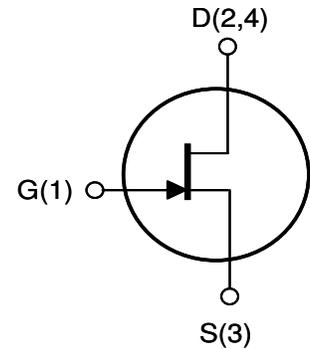
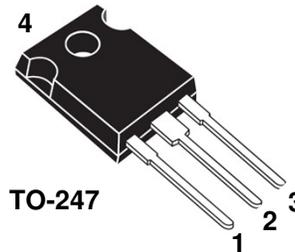
Product Summary		
$BV_{DS}$	1200	V
$R_{DS(on)max}$	0.045	$\Omega$

**Features:**

- Positive Temperature Coefficient for Ease of Paralleling
- Extremely Fast Switching with No "Tail" Current at 150 °C
- $R_{DS(on)}$  typical of 0.035  $\Omega$
- Voltage Controlled
- Low Gate Charge
- Low Intrinsic Capacitance

**Applications:**

- Solar Inverter
- SMPS
- Power Factor Correction
- Induction Heating
- UPS
- Motor Drive



Internal Schematic

**MAXIMUM RATINGS**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	$I_{D, TC=25}$	$T_C = 25\text{ °C}$	48	A
	$I_{D, TC=100}$	$T_C = 100\text{ °C}$	30	
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	$T_j = 25\text{ °C}$	140	A
Short Circuit Withstand Time	$t_{SC}$	$V_{DD} < 800\text{ V}, T_C < 125\text{ °C}$	50	$\mu\text{s}$
Power Dissipation	$P_D$	$T_C = 25\text{ °C}$	208	W
Gate-Source Voltage	$V_{GS}$	AC <sup>(2)</sup>	-15 to +15	V
Operating and Storage Temperature	$T_j, T_{stg}$		-55 to +150	°C
Lead Temperature for Soldering	$T_{sold}$	1/8" from case < 10 s	260	°C

<sup>(1)</sup> Pulse width limited by maximum junction temperature

<sup>(2)</sup>  $R_{g(EXT)} = 1\text{ ohm}, t_p \leq 200\text{ns}$ , see Figure 5 for static conditions

**THERMAL CHARACTERISTICS**

Parameter	Symbol	Value		Unit
		Typ	Max	
Thermal Resistance, junction-to-case	$R_{th,JC}$	-	0.6	°C / W
Thermal Resistance, junction-to-ambient	$R_{th,JA}$	-	50	

**ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Conditions	Value			Unit
			Min	Typ	Max	

**Off Characteristics**

Drain-Source Blocking Voltage	$BV_{DS}$	$V_{GS} = -15\text{ V}, I_D = 1200\ \mu\text{A}$	1200	-	-	V
Total Drain Leakage Current	$I_{DSS}$	$V_{DS} = 1200\text{ V}, V_{GS} = -15\text{ V}, T_j = 25^\circ\text{C}$	-	20	-	$\mu\text{A}$
		$V_{DS} = 1200\text{ V}, V_{GS} = -15\text{ V}, T_j = 150^\circ\text{C}$	-	200	-	
Total Gate Reverse Leakage	$I_{GSS}$	$V_{GS} = -15\text{ V}, V_{DS} = 0\text{ V}$	-	-0.2	-0.6	mA
		$V_{GS} = -15\text{ V}, V_{DS} = 1200\text{ V}$	-	-0.2	-	

**On Characteristics**

Drain-Source On-resistance	$R_{DS(on)}$	$I_D = 30\text{ A}, V_{GS} = 2\text{ V}, T_j = 25^\circ\text{C}$	-	0.035	0.045	$\Omega$
		$I_D = 30\text{ A}, V_{GS} = 2\text{ V}, T_j = 100^\circ\text{C}$	-	0.06	-	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = 1\text{ V}, I_D = 70\text{ mA}$	-	-5	-	V
Gate Forward Current	$I_{GFWD}$	$V_{GS} = 2\text{ V}$	-	41	-	$\mu\text{A}$
Gate Resistance	$R_G$	$f = 1\text{ MHz}, \text{ drain-source shorted}$	-	4	-	$\Omega$
	$R_{G(on)}$	$V_{GS} > 2.7\text{ V}; \text{ See Figure 5}$	-	0.25	-	$\Omega$

**Dynamic Characteristics**

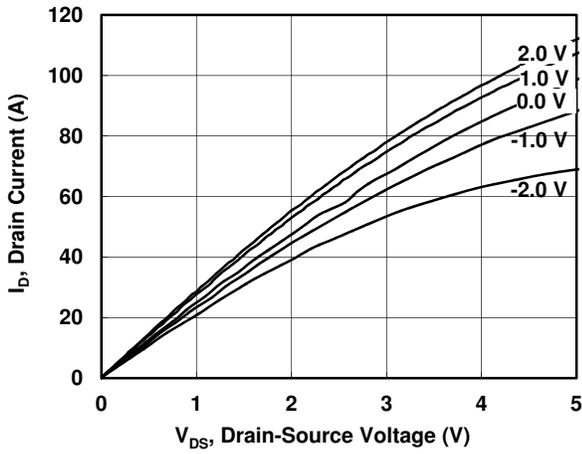
Input Capacitance	$C_{iss}$	$V_{DD} = 100\text{ V}, V_{GS} = -15\text{ V}, f = 100\text{ kHz}$	-	510	-	pF
Output Capacitance	$C_{oss}$		-	160	-	
Reverse Transfer Capacitance	$C_{rss}$		-	160	-	
Effective Output Capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0\text{ V to } 600\text{ V}, V_{GS} = -15\text{ V}$	-	100	-	

**Switching Characteristics**

Turn-on Delay	$t_{on}$	$V_{DS} = 600\text{ V}, I_D = 30\text{ A}, \text{ Inductive Load}, T_j = 25^\circ\text{C}, \text{ Gate Driver} = +15\text{ V}, -15\text{ V}, R_{g(EXT)} = 1\ \Omega$	-	TBD	-	ns
Rise Time	$t_r$		-	TBD	-	
Turn-off Delay	$t_{off}$		-	TBD	-	
Fall Time	$t_f$		-	TBD	-	
Turn-on Energy	$E_{on}$		-	TBD	-	
Turn-off Energy	$E_{off}$	$V_{DS} = 600\text{ V}, I_D = 30\text{ A}, \text{ Inductive Load}, T_j = 150^\circ\text{C}, \text{ Gate Driver} = +15\text{ V}, -15\text{ V}, R_{g(EXT)} = 1\ \Omega$	-	TBD	-	$\mu\text{J}$
Total Switching Energy	$E_{ts}$		-	TBD	-	
Turn-on Delay	$t_{on}$		-	TBD	-	
Rise Time	$t_r$		-	TBD	-	
Turn-off Delay	$t_{off}$		-	TBD	-	
Fall Time	$t_f$	$V_{DS} = 600\text{ V}, I_D = 15\text{ A}, V_{GS} = +2.5\text{ V}$	-	TBD	-	nC
Turn-on Energy	$E_{on}$		-	TBD	-	
Turn-off Energy	$E_{off}$		-	TBD	-	
Total Switching Energy	$E_{ts}$		-	TBD	-	
Total Gate Charge	$Q_g$		-	65	-	
Gate-Source Charge	$Q_{gs}$	-	4	-		
Gate-Drain Charge	$Q_{gd}$	-	54	-		

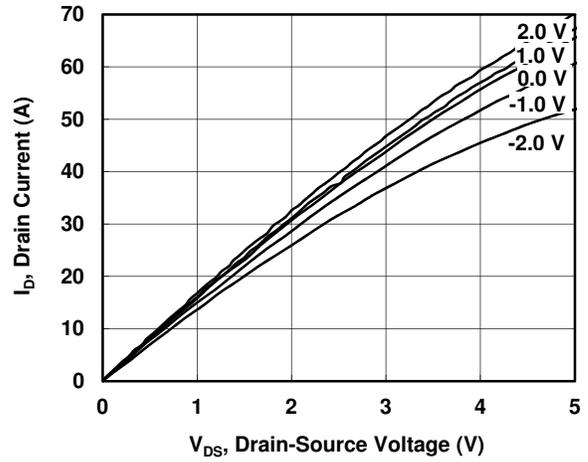
**Figure 1. Typical Output Characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$



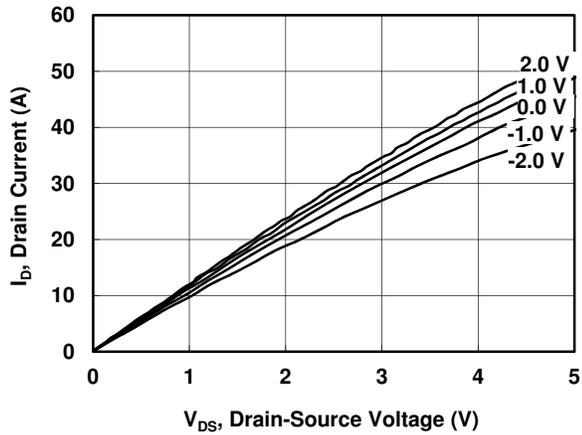
**Figure 2. Typical Output Characteristics**

$I_D = f(V_{DS}); T_j = 100\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$



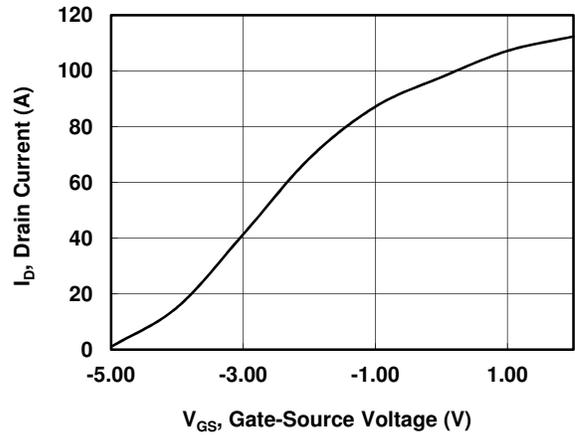
**Figure 3. Typical Output Characteristics**

$I_D = f(V_{DS}); T_j = 150\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$



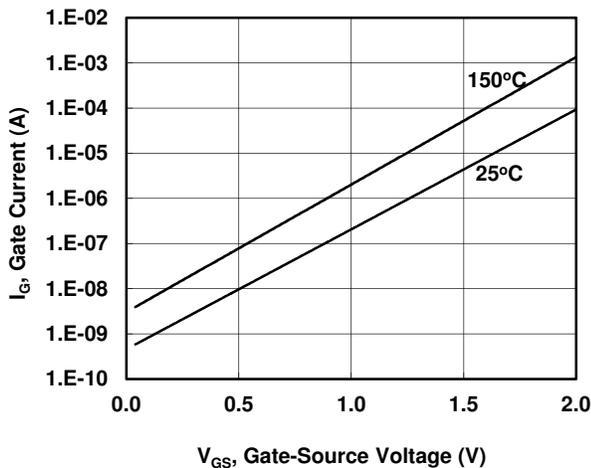
**Figure 4. Typical Transfer Characteristics**

$I_D = f(V_{GS}); V_{DS} = 5\text{ V}; T_j = 25\text{ }^\circ\text{C}$



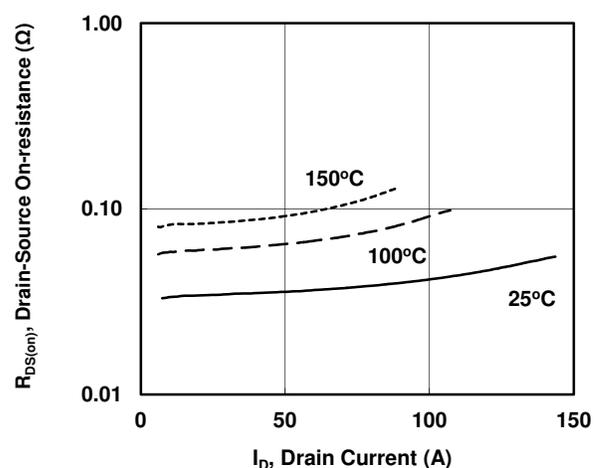
**Figure 5. Gate Current**

$I_G = f(V_{GS}); \text{parameter: } T_j$



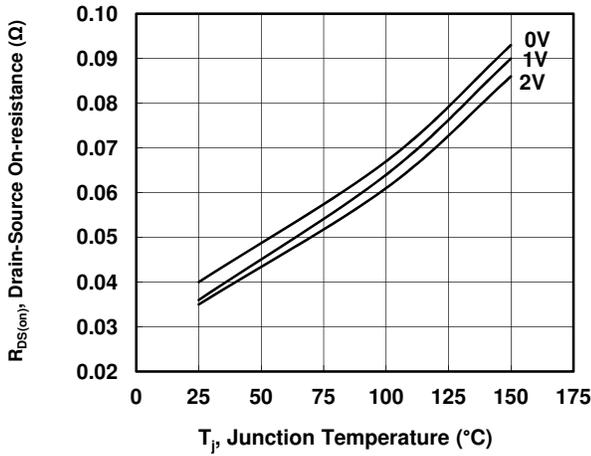
**Figure 6. Drain-Source On-resistance**

$R_{DS(on)} = f(I_D); V_{GS} = 2.0; \text{parameter: } T_j$



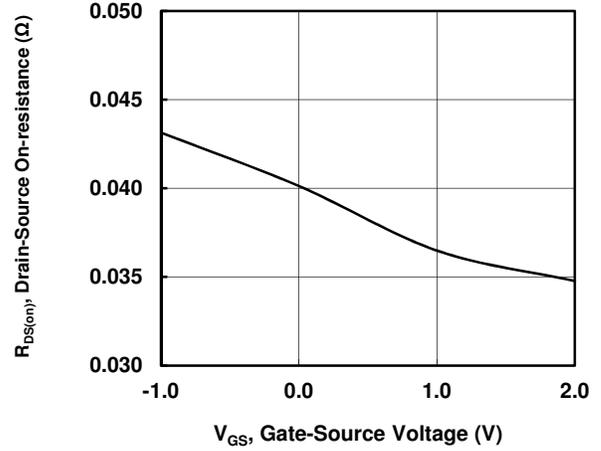
**Figure 7. Drain-Source On-resistance**

$R_{DS(on)} = f(T_j); I_D = 30A; \text{parameter: } V_{GS}$



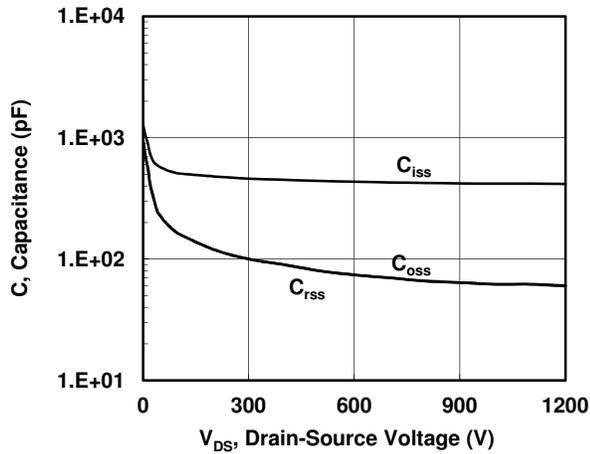
**Figure 8. Drain-Source On-resistance**

$R_{DS(on)} = f(V_{GS}); I_D = 30A; T_j = 25^\circ C$



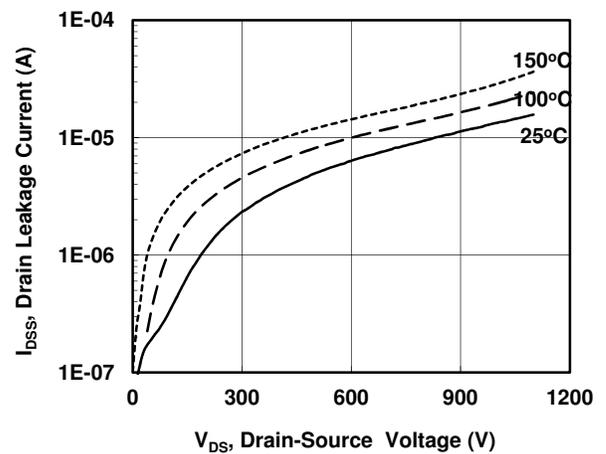
**Figure 9. Typical Capacitance**

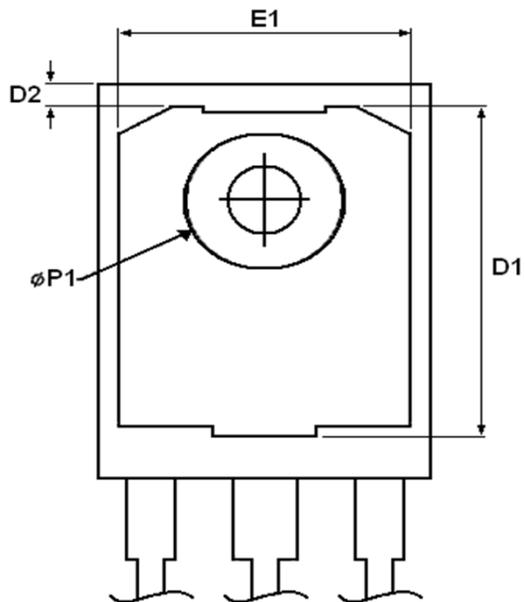
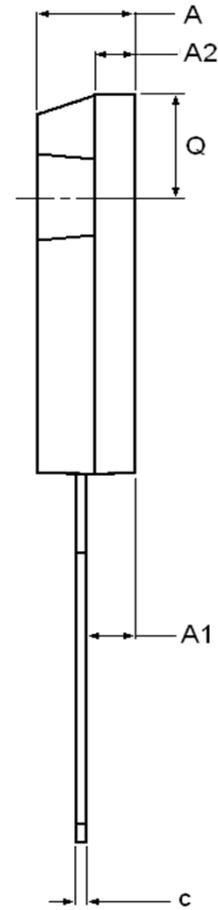
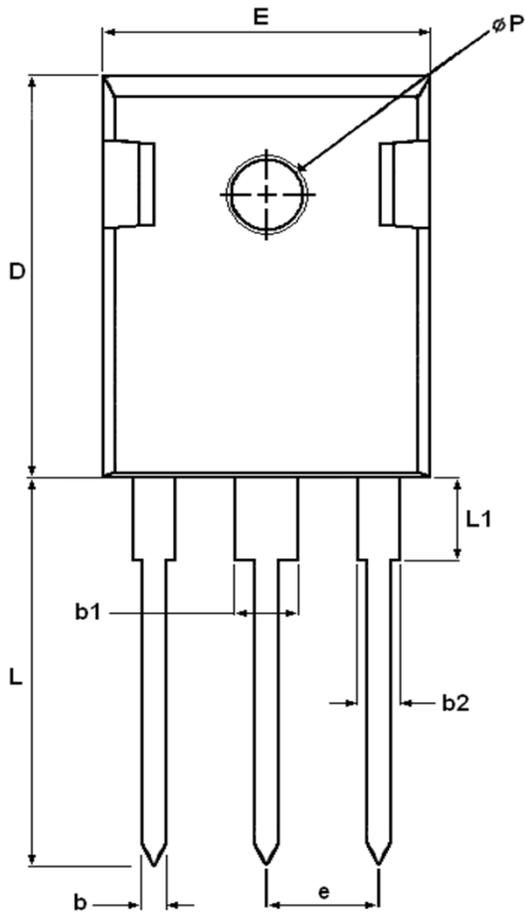
$C = f(V_{DS}); V_{GS} = -15V; f = 100\text{ kHz}$



**Figure 10. Drain-Source Leakage**

$I_{DSS} = f(V_{DS}); V_{GS} = -15V; \text{parameter: } T_j$





DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.090	0.100
A2	1.853	2.108	0.073	0.083
b	1.073	1.327	0.042	0.052
b1	2.873	3.381	0.113	0.133
b2	1.903	2.386	0.042	0.052
c	0.600	0.752	0.024	0.029
D	20.823	21.077	0.820	0.830
D1	17.393	17.647	0.685	0.695
D2	1.063	1.317	0.042	0.052
e	5.450		0.215	
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
L	20.053	20.307	0.789	0.799
L1	4.168	4.472	0.165	0.175
Q	6.043	6.297	0.238	0.248
ØP	3.560	3.660	0.140	0.144
ØP1	7.063	7.317	0.278	0.288

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